

[54] **DUAL HEAT SINK FOR ELECTRONIC SEMICONDUCTOR DEVICES**

[75] **Inventor:** Alfred F. McCarthy, Belmont, N.H.

[73] **Assignee:** Aavid Engineering, Inc., Laconia, N.H.

[\*\*] **Term:** 14 Years

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[51] **Int. Cl.** ..... D13-03

[52] **U.S. Cl.** ..... D13/23

[58] **Field of Search** ..... D13/23; 174/16 HS; 357/81; 165/80, 80 A, 80 B

[56] **References Cited**

**U.S. PATENT DOCUMENTS**

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*Primary Examiner*—Susan J. Lucas  
*Attorney, Agent, or Firm*—James E. Mrose

[57] **CLAIM**

The ornamental design for a dual heat sink for electronic semiconductor devices, substantially as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a dual heat sink for electronic semiconductor devices showing my new design; the broken lines being shown for illustrative purposes, only;

FIG. 2 is a front elevational view of the same heat sink;

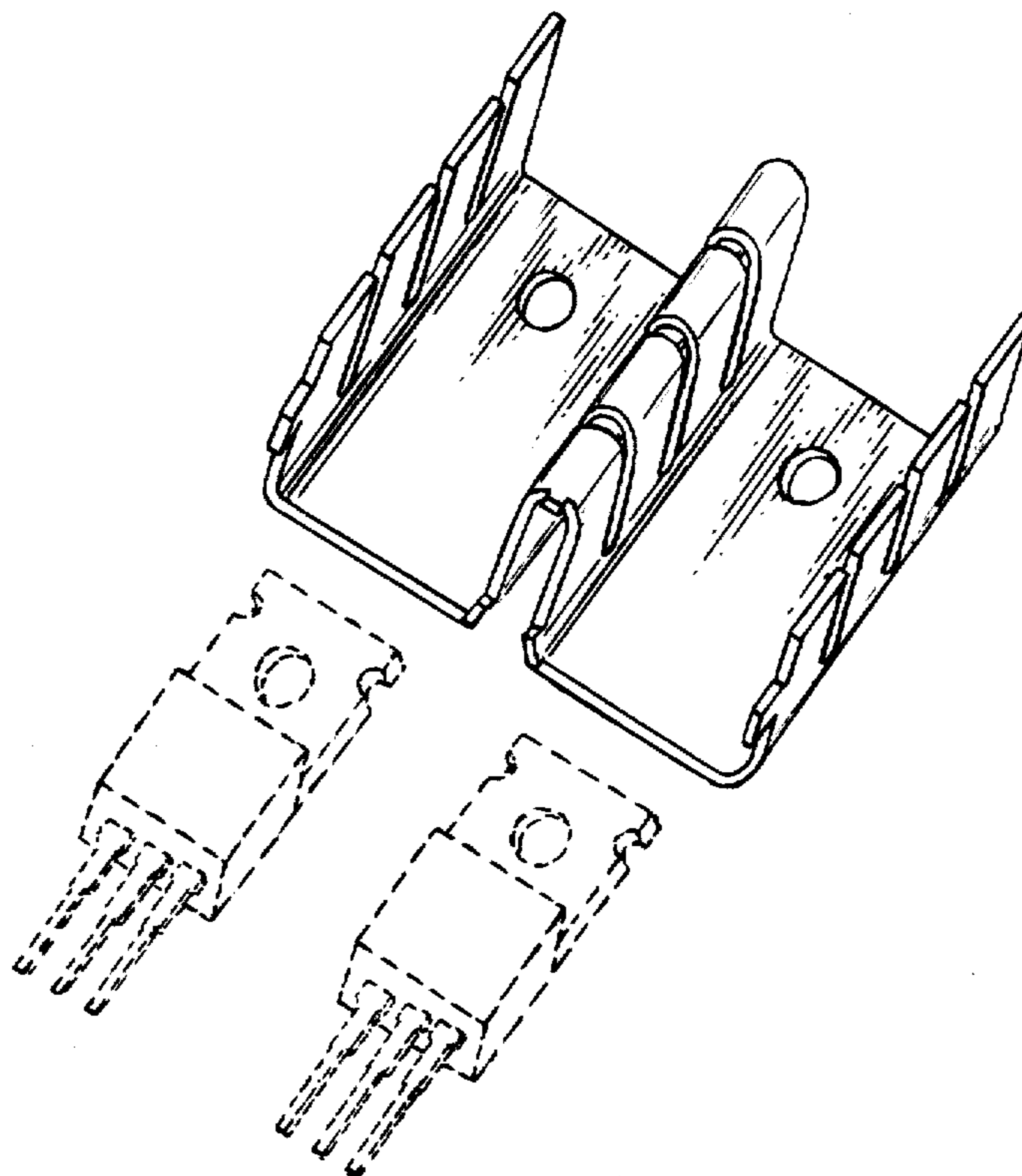
FIG. 3 is a rear elevational view thereof;

FIG. 4 is a side elevational view thereof, looking toward the right side of the heat sink as it is shown in FIG. 1;

FIG. 5 is a side elevational view thereof, looking toward the left side of the heat sink as it is shown in FIG. 1;

FIG. 6 is a top plan view thereof; and

FIG. 7 is a bottom plan view thereof.



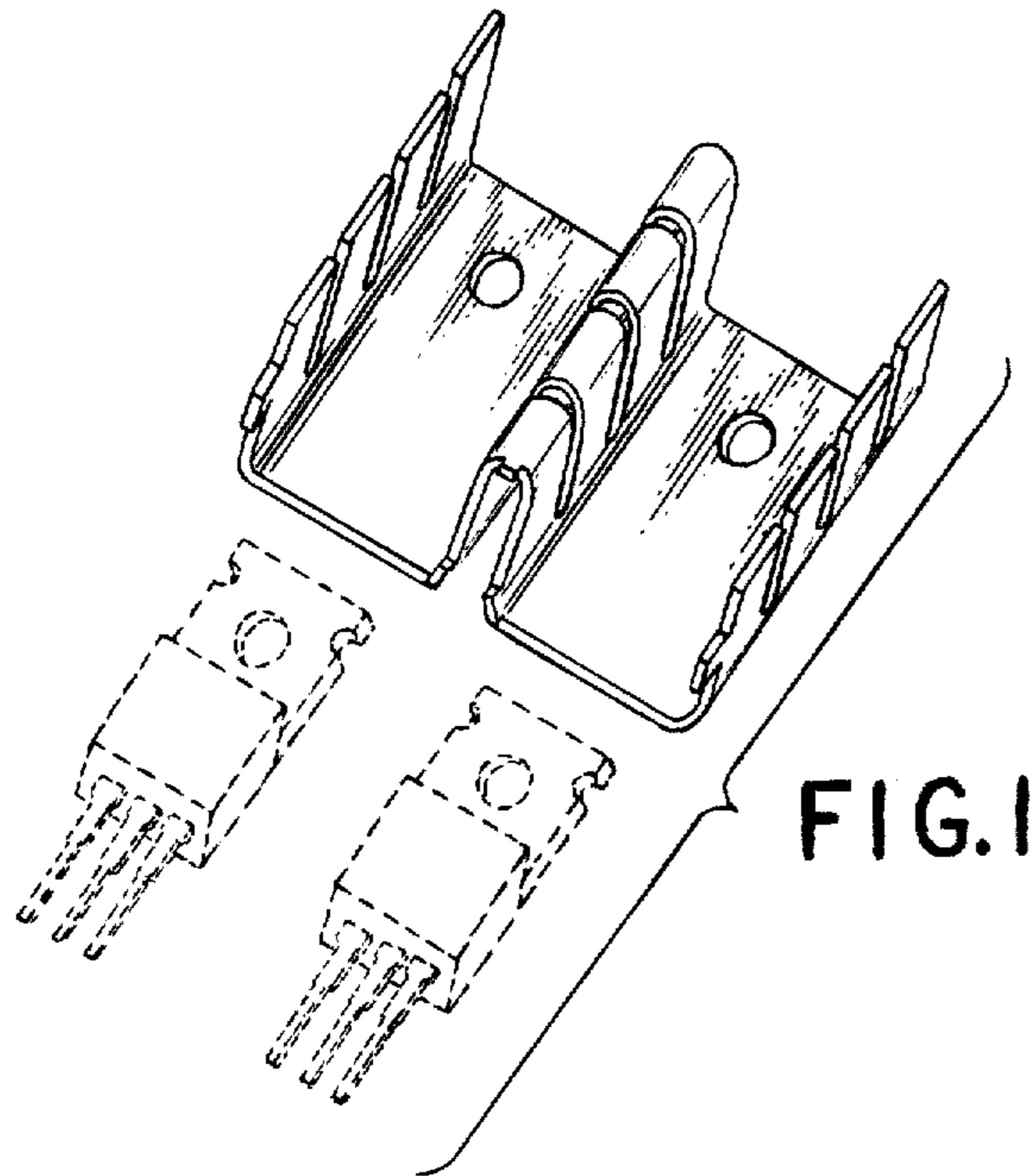


FIG. 1

FIG. 2

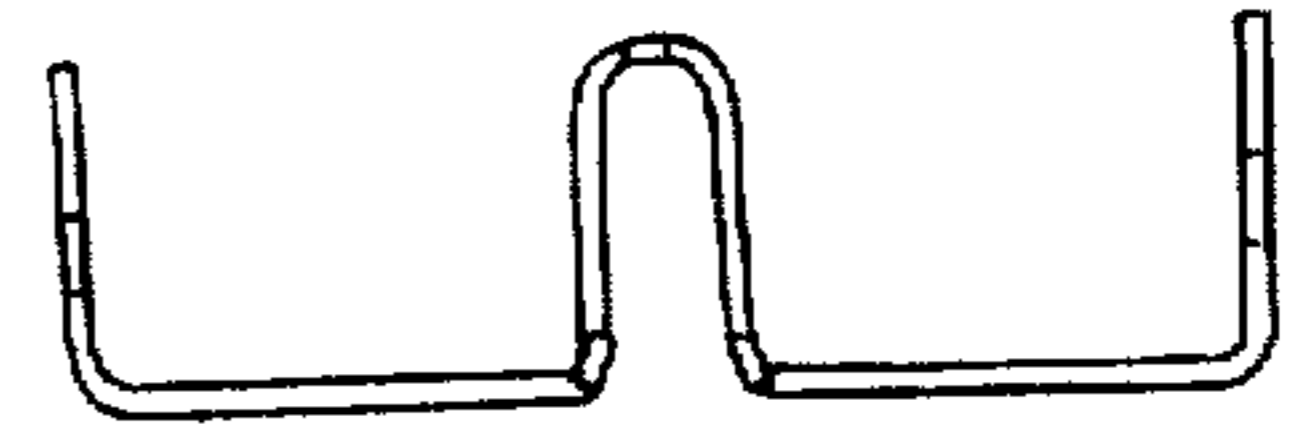


FIG. 3

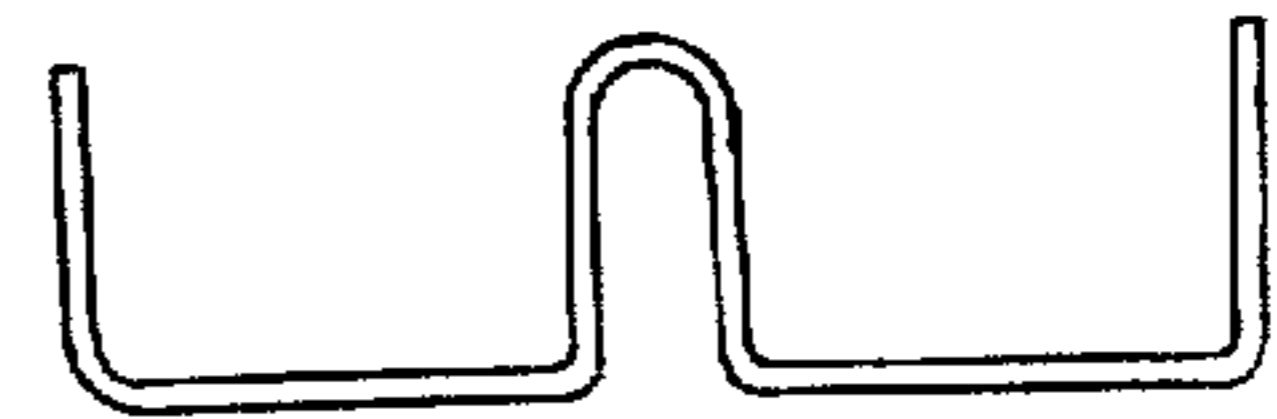


FIG. 4



FIG. 5

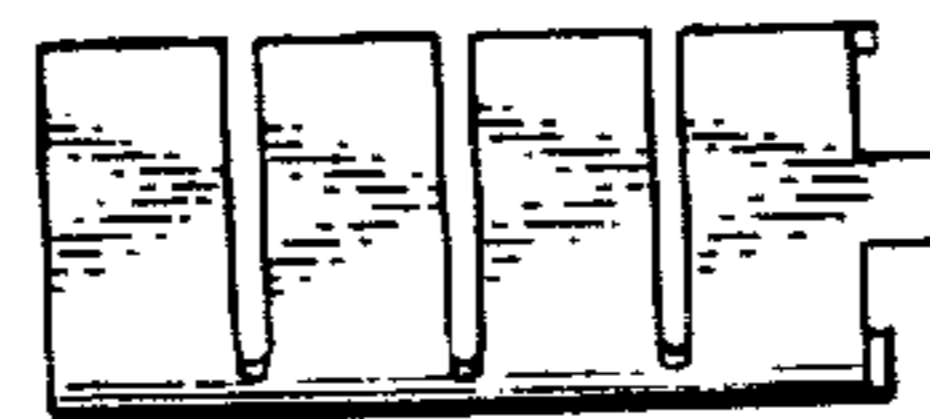


FIG. 6

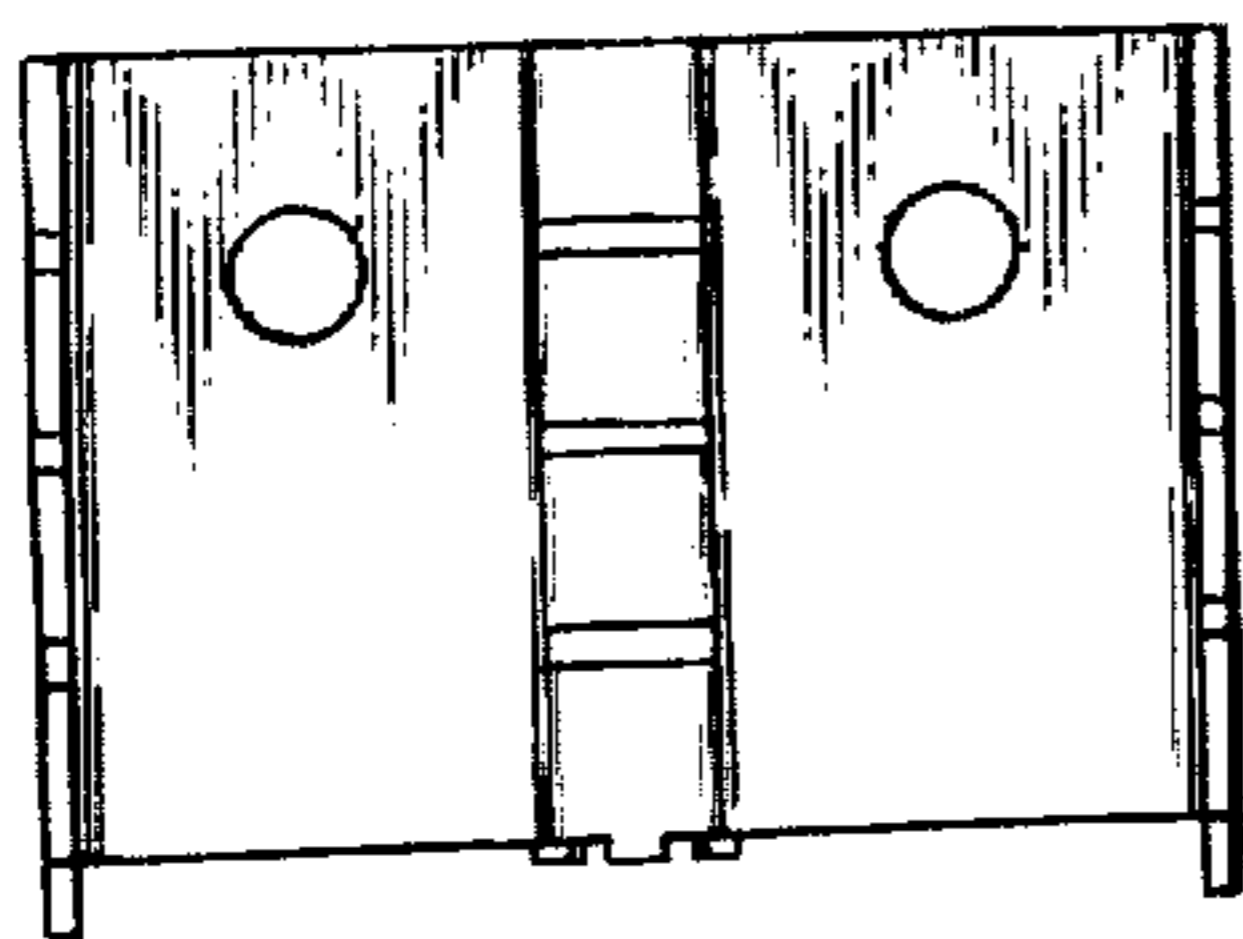


FIG. 7

